Low-power 2-input NAND gate Rev. 10 — 19 September 2024

1. General description

The 74AUP1G00 is a single 2-input NAND gate. Schmitt-trigger action at all inputs makes the circuit tolerant of slower input rise and fall times. This device ensures very low static and dynamic power consumption across the entire V_{CC} range from 0.8 V to 3.6 V. This device is fully specified for partial power down applications using I_{OFF}. The I_{OFF} circuitry disables the output, preventing the damaging backflow current through the device when it is powered down.

2. Features and benefits

- Wide supply voltage range from 0.8 V to 3.6 V
- CMOS low power dissipation
- High noise immunity
- Complies with JEDEC standards:
 - JESD8-12 (0.8 V to 1.3 V)
 - JESD8-11 (0.9 V to 1.65 V)
 - JESD8-7 (1.65 V to 1.95 V)
 - JESD8-5 (2.3 V to 2.7 V)
 - JESD8C (2.7 V to 3.6 V)
- Low static power consumption; I_{CC} = 0.9 µA (maximum)
- Latch-up performance exceeds 100 mA per JESD 78 Class II
- Overvoltage tolerant inputs to 3.6 V
- Low noise overshoot and undershoot < 10 % of V_{CC}
- I_{OFF} circuitry provides partial Power-down mode operation
- Multiple package options
- ESD protection:
 - HBM: ANSI/ESDA/JEDEC JS-001 class 3A exceeds 5000 V
 - CDM: ANSI/ESDA/JEDEC JS-002 class C3 exceeds 1000 V
- Specified from -40 °C to +85 °C and -40 °C to +125 °C

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3. Ordering information

ľ	Table	1.	Ordering	information

Type number	Package	Package							
	Temperature range	Name	Description	Version					
74AUP1G00GW	-40 °C to +125 °C	TSSOP5	plastic thin shrink small outline package; 5 leads; body width 1.25 mm	<u>SOT353-1</u>					
74AUP1G00GM	-40 °C to +125 °C	XSON6	plastic extremely thin small outline package; no leads; 6 terminals; body 1 × 1.45 × 0.5 mm	<u>SOT886</u>					
74AUP1G00GN	-40 °C to +125 °C	XSON6	extremely thin small outline package; no leads; 6 terminals; body 0.9 × 1.0 × 0.35 mm	<u>SOT1115</u>					
74AUP1G00GS	-40 °C to +125 °C	XSON6	extremely thin small outline package; no leads; 6 terminals; body 1.0 × 1.0 × 0.35 mm	<u>SOT1202</u>					
74AUP1G00GX	-40 °C to +125 °C	X2SON5	plastic thermal enhanced extremely thin small outline package; no leads; 5 terminals; body 0.8 × 0.8 × 0.32 mm	<u>SOT1226-3</u>					
74AUP1G00GZ	-40 °C to +125 °C	XSON5	plastic thermal enhanced extremely thin small outline package with side-wettable flanks (SWF); no leads; 5 terminals; body 1.1 × 0.85 × 0.5 mm	<u>SOT8065-1</u>					

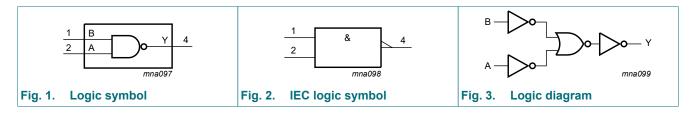
4. Marking

Table 2. Marking

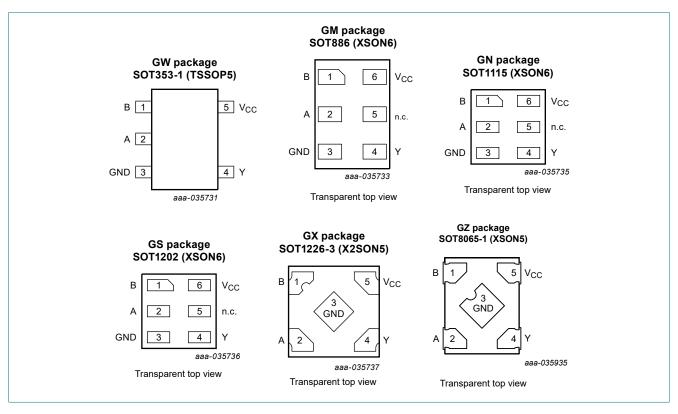
Type number	Marking code [1]
74AUP1G00GW	рА
74AUP1G00GM	pA
74AUP1G00GN	pA
74AUP1G00GS	pA
74AUP1G00GX	pA
74AUP1G00GZ	pA

[1] The pin 1 indicator is located on the lower left corner of the device, below the marking code.

5. Functional diagram



6. Pinning information



6.1. Pinning

6.2. Pin description

Table 3. Pin description

Symbol	Pin		Description
	TSSOP5, X2SON5 and XSON5	XSON6	
В	1	1	data input
A	2	2	data input
GND	3	3	ground (0 V)
Y	4	4	data output
n.c.	-	5	not connected
V _{CC}	5	6	supply voltage

7. Functional description

Table 4. Function table

H = HIGH voltage level; L = LOW voltage level.

Input	Output	
Α	В	Y
L	L	Н
L	Н	Н
Н	L	Н
Н	Н	L

8. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134). Voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions		Min	Max	Unit
V _{CC}	supply voltage			-0.5	+4.6	V
I _{IK}	input clamping current	V _I < 0 V		-50	-	mA
VI	input voltage		[1]	-0.5	+4.6	V
I _{OK}	output clamping current	V _O < 0 V		-50	-	mA
Vo	output voltage	Active mode	[1]	-0.5	V _{CC} + 0.5	V
		Power-down mode; V_{CC} = 0 V	[1]	-0.5	+4.6	V
I _O	output current	$V_{O} = 0 V$ to V_{CC}		-	±20	mA
I _{CC}	supply current			-	+50	mA
I _{GND}	ground current			-50	-	mA
T _{stg}	storage temperature			-65	+150	°C
P _{tot}	total power dissipation	T_{amb} = -40 °C to +125 °C	[2]	-	250	mW

[1] The minimum input and output voltage ratings may be exceeded if the input and output current ratings are observed.

[2] For SOT353-1 (TSSOP5) package: P_{tot} derates linearly with 3.3 mW/K above 74 °C.

For SOT886 (XSON6) package: P_{tot} derates linearly with 3.3 mW/K above 74 °C.

For SOT1115 (XSON6) package: Ptot derates linearly with 3.2 mW/K above 71 °C.

For SOT1202 (XSON6) package: P_{tot} derates linearly with 3.3 mW/K above 74 °C.

For SOT1226-3 (X2SON5) package: Ptot derates linearly with 3.0 mW/K above 67 °C.

For SOT8065-1 (XSON5) package: Ptot derates linearly with 3.2 mW/K above 72 °C.

9. Recommended operating conditions

Table 6. Recommended operating conditions

Symbol	Parameter	Conditions	Min	Max	Unit			
V _{CC}	supply voltage		0.8	3.6	V			
VI	input voltage		0	3.6	V			
Vo	output voltage	Active mode	0	V _{CC}	V			
		Power-down mode; V_{CC} = 0 V	0	3.6	V			
T _{amb}	ambient temperature		-40	+125	°C			
Δt/ΔV	input transition rise and fall rate	V _{CC} = 0.8 V to 3.6 V	0	200	ns/V			

10. Static characteristics

Table 7. Static characteristics

At recommended operating conditions; voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	Min	Тур	Мах	Unit
T _{amb} = 2	25 °C					_
VIH	HIGH-level input voltage	V _{CC} = 0.8 V	0.70×V _{CC}	-	-	V
		V _{CC} = 0.9 V to 1.95 V	$0.65 \times V_{CC}$	-	-	V
		V _{CC} = 2.3 V to 2.7 V	1.6	-	-	V
		V _{CC} = 3.0 V to 3.6 V	2.0	-	Max - - 0.30×V _{CC} 0.35×V _{CC} 0.35×V _{CC} 0.7 0.9 - - 0.7 0.9 - - - - - - - - 0.1 0.3×V _{CC} 0.31 0.31 0.31 0.44 0.31 0.44 ±0.1 ±0.2 ±0.2	V
V _{IL}	LOW-level input voltage	V _{CC} = 0.8 V	-	-	0.30×V _{CC}	V
		V _{CC} = 0.9 V to 1.95 V	-	-	0.35×V _{CC}	V
		V _{CC} = 2.3 V to 2.7 V	-	-	0.7	V
		V _{CC} = 3.0 V to 3.6 V	-	-	0.9	V
V _{OH}	HIGH-level output voltage	$V_{I} = V_{IH} \text{ or } V_{IL}$				
		I_{O} = -20 µA; V_{CC} = 0.8 V to 3.6 V	V _{CC} - 0.1	-	-	V
		I _O = -1.1 mA; V _{CC} = 1.1 V	0.75×V _{CC}	-	-	V
		I _O = -1.7 mA; V _{CC} = 1.4 V	1.11	-	-	V
		I _O = -1.9 mA; V _{CC} = 1.65 V	1.32	-	-	V
		I _O = -2.3 mA; V _{CC} = 2.3 V	2.05	-	-	V
		I _O = -3.1 mA; V _{CC} = 2.3 V	1.9	-	-	V
		I _O = -2.7 mA; V _{CC} = 3.0 V	2.72	-	-	V
		I _O = -4.0 mA; V _{CC} = 3.0 V	2.6	-	-	V
V _{OL}	LOW-level output voltage	V _I = V _{IH} or V _{IL}				
		I_{O} = 20 µA; V_{CC} = 0.8 V to 3.6 V	-	-	0.1	V
		I _O = 1.1 mA; V _{CC} = 1.1 V	-	-	0.3×V _{CC}	V
		I _O = 1.7 mA; V _{CC} = 1.4 V	-	-	0.31	V
		I _O = 1.9 mA; V _{CC} = 1.65 V	-	-	0.31	V
		I _O = 2.3 mA; V _{CC} = 2.3 V	-	-	0.31	V
		I _O = 3.1 mA; V _{CC} = 2.3 V	-	-	0.44	V
		I _O = 2.7 mA; V _{CC} = 3.0 V	-	-	0.31	V
		I _O = 4.0 mA; V _{CC} = 3.0 V	-	-	$\begin{array}{c c} 0.35 \times V_{CC} \\ 0.7 \\ 0.9 \\ \hline \\ - \\ - \\ - \\ - \\ - \\ - \\ - \\ - \\ 0.1 \\ 0.3 \times V_{CC} \\ 0.31 \\ 0.31 \\ 0.31 \\ 0.31 \\ 0.44 \\ 0.31 \\ 0.44 \\ \pm 0.1 \\ \pm 0.2 \\ \end{array}$	V
I _I	input leakage current	V_{I} = GND to 3.6 V; V_{CC} = 0 V to 3.6 V	-	-	±0.1	μA
I _{OFF}	power-off leakage current	$V_1 \text{ or } V_0 = 0 \text{ V to } 3.6 \text{ V}; V_{CC} = 0 \text{ V}$	-	-	±0.2	μA
ΔI _{OFF}	additional power-off leakage current	$V_{I} \text{ or } V_{O} = 0 \text{ V to } 3.6 \text{ V};$ $V_{CC} = 0 \text{ V to } 0.2 \text{ V}$	-	-	±0.2	μA
I _{CC}	supply current	$V_{I} = GND \text{ or } V_{CC}; I_{O} = 0 \text{ A};$ $V_{CC} = 0.8 \text{ V to } 3.6 \text{ V}$	-	-	0.5	μA
ΔI _{CC}	additional supply current	$V_1 = V_{CC} - 0.6 V; I_0 = 0 A; V_{CC} = 3.3 V$ [1]	-	-	40	μA
CI	input capacitance	V_{CC} = 0 V to 3.6 V; V _I = GND or V _{CC}	-	0.8	-	pF
Co	output capacitance	$V_0 = GND; V_{CC} = 0 V$	-	1.7	-	pF

Low-power 2-input NAND gate

Symbol	Parameter	Conditions	Min	Тур	Мах	Unit
T _{amb} = -	-40 °C to +85 °C					
VIH	HIGH-level input voltage	V _{CC} = 0.8 V	0.70×V _{CC}	-	-	V
		V _{CC} = 0.9 V to 1.95 V	0.65×V _{CC}	-	-	V
		V _{CC} = 2.3 V to 2.7 V	1.6	-	-	V
		V _{CC} = 3.0 V to 3.6 V	2.0	-	-	V
V _{IL}	LOW-level input voltage	V _{CC} = 0.8 V	-	-	0.30×V _{CC}	V
		V _{CC} = 0.9 V to 1.95 V	-	-	$0.35 \times V_{CC}$	V
		V _{CC} = 2.3 V to 2.7 V	-	-	0.7	V
		V _{CC} = 3.0 V to 3.6 V	-	-	· · · · · · · · · · · · · · · · · · ·	V
V _{OH}	HIGH-level output voltage	$V_{I} = V_{IH} \text{ or } V_{IL}$				
		$I_{\rm O}$ = -20 µA; V _{CC} = 0.8 V to 3.6 V	V _{CC} - 0.1	-	-	V
		I _O = -1.1 mA; V _{CC} = 1.1 V	0.7×V _{CC}	-	-	V
		I _O = -1.7 mA; V _{CC} = 1.4 V	1.03	-	-	V
		I _O = -1.9 mA; V _{CC} = 1.65 V	1.30	-	-	V
		I _O = -2.3 mA; V _{CC} = 2.3 V	1.97	-	- - 0.30×V _{CC} 0.35×V _{CC} 0.35×V _{CC} 0.7 0.7 0.7 0.7 0.7 0.35×V _{CC} 0.7 0.7 0.1 - - 0.1 0.3×V _{CC} 0.37 0.35 0.37 0.33 0.45 10.3×V _{CC} 0.37 0.35 0.33 0.45 ±0.5 ±0.6 0.9 50 - - - 0.25×V _{CC} 0.30×V _{CC}	V
		I _O = -3.1 mA; V _{CC} = 2.3 V	1.85	-		V
		I _O = -2.7 mA; V _{CC} = 3.0 V	2.67	-		V
		I _O = -4.0 mA; V _{CC} = 3.0 V	2.55	-	-	V
V _{OL}	LOW-level output voltage	$V_{I} = V_{IH} \text{ or } V_{IL}$				
		I_{O} = 20 µA; V_{CC} = 0.8 V to 3.6 V	-	-	0.1	V
		I _O = 1.1 mA; V _{CC} = 1.1 V	-	-	0.3×V _{CC}	V
		I _O = 1.7 mA; V _{CC} = 1.4 V	-	-	0.37	V
		I _O = 1.9 mA; V _{CC} = 1.65 V	-	-	0.35	V
		I _O = 2.3 mA; V _{CC} = 2.3 V	-	-	0.33	V
		I _O = 3.1 mA; V _{CC} = 2.3 V	-	-	0.45	V
		I _O = 2.7 mA; V _{CC} = 3.0 V	-	-	0.33	V
		I _O = 4.0 mA; V _{CC} = 3.0 V	-	-	0.45	V
l _l	input leakage current	V_{I} = GND to 3.6 V; V_{CC} = 0 V to 3.6 V	-	-	- - 0.30×V _{CC} 0.35×V _{CC} 0.35×V _{CC} 0.7 0.9 - - - - - - - - - 0.1 0.3×V _{CC} 0.1 0.3×V _{CC} 0.37 0.35 0.33 0.45 ±0.5	μA
I _{OFF}	power-off leakage current	V_1 or V_0 = 0 V to 3.6 V; V_{CC} = 0 V	-	-	±0.5	μA
∆I _{OFF}	additional power-off leakage current	$V_1 \text{ or } V_0 = 0 \text{ V to } 3.6 \text{ V};$ $V_{CC} = 0 \text{ V to } 0.2 \text{ V}$	-	-	±0.6	μA
I _{CC}	supply current	V_I = GND or V_{CC} ; I_O = 0 A; V_{CC} = 0.8 V to 3.6 V	-	-	0.9	μA
ΔI _{CC}	additional supply current	$V_{I} = V_{CC} - 0.6 \text{ V}; I_{O} = 0 \text{ A}; V_{CC} = 3.3 \text{ V}$ [1	- 1	-	50	μA
VIL L VOH H VOH L VIH L	-40 °C to +125 °C					
V _{IH}	HIGH-level input voltage	V _{CC} = 0.8 V	0.75×V _{CC}	-	-	V
		V _{CC} = 0.9 V to 1.95 V	0.70×V _{CC}	-	-	V
		V _{CC} = 2.3 V to 2.7 V	1.6	-	-	V
		V _{CC} = 3.0 V to 3.6 V	2.0	-	-	V
V _{IL}	LOW-level input voltage	V _{CC} = 0.8 V	-	-	0.25×V _{CC}	V
		V _{CC} = 0.9 V to 1.95 V	-	-	0.30×V _{CC}	V
		V _{CC} = 2.3 V to 2.7 V	-	-	0.7	V
		V _{CC} = 3.0 V to 3.6 V	-	-	0.9	V

Low-power 2-input NAND gate

Symbol	Parameter	Conditions	Min	Тур	Мах	Unit
V _{OH}	HIGH-level output voltage	V _I = V _{IH} or V _{IL}				
		I_{O} = -20 µA; V_{CC} = 0.8 V to 3.6 V	V _{CC} - 0.11	-	-	V
		I _O = -1.1 mA; V _{CC} = 1.1 V	0.6×V _{CC}	-	-	V
		I _O = -1.7 mA; V _{CC} = 1.4 V	0.93	-	-	V
		I _O = -1.9 mA; V _{CC} = 1.65 V	1.17	-	-	V
		I _O = -2.3 mA; V _{CC} = 2.3 V	1.77	-	-	V
		I _O = -3.1 mA; V _{CC} = 2.3 V	1.67	-	-	V
		I _O = -2.7 mA; V _{CC} = 3.0 V	2.40	-	-	V
		I _O = -4.0 mA; V _{CC} = 3.0 V	2.30	-		V
V _{OL}	LOW-level output voltage	$V_{I} = V_{IH} \text{ or } V_{IL}$				
		$I_0 = 20 \ \mu\text{A}; \ V_{CC} = 0.8 \ \text{V} \text{ to } 3.6 \ \text{V}$	-	-	0.11	V
		I _O = 1.1 mA; V _{CC} = 1.1 V	-	-	0.33×V _{CC}	V
		I _O = 1.7 mA; V _{CC} = 1.4 V	-	-	0.41	V
		I _O = 1.9 mA; V _{CC} = 1.65 V	-	-	0.39	V
		I _O = 2.3 mA; V _{CC} = 2.3 V	-	-	0.36	V
		I _O = 3.1 mA; V _{CC} = 2.3 V	-	-	0.50	V
		I _O = 2.7 mA; V _{CC} = 3.0 V	-	-	0.36	V
		I _O = 4.0 mA; V _{CC} = 3.0 V	-	-	0.50	V
l	input leakage current	V_{I} = GND to 3.6 V; V_{CC} = 0 V to 3.6 V	-	-	±0.75	μA
I _{OFF}	power-off leakage current	$V_{I} \text{ or } V_{O} = 0 \text{ V to } 3.6 \text{ V}; V_{CC} = 0 \text{ V}$	-	-	±0.75	μA
∆I _{OFF}	additional power-off leakage current	$V_{I} \text{ or } V_{O} = 0 \text{ V to } 3.6 \text{ V};$ $V_{CC} = 0 \text{ V to } 0.2 \text{ V}$	-	-	±0.75	μA
I _{CC}	supply current	$V_{I} = GND \text{ or } V_{CC}; I_{O} = 0 \text{ A};$ $V_{CC} = 0.8 \text{ V to } 3.6 \text{ V}$	-	-	1.4	μA
ΔI _{CC}	additional supply current	$V_{I} = V_{CC} - 0.6 \text{ V}; I_{O} = 0 \text{ A}; V_{CC} = 3.3 \text{ V}$ [1]	-	-	75	μA

[1] One input at V_{CC} - 0.6 V, other input at V_{CC} or GND.

11. Dynamic characteristics

Table 8. Dynamic characteristics

Voltages are referenced to GND (ground = 0 V); for test circuit see Fig. 5

Symbol	Parameter	Conditions	Min	Typ [1]	Max	Unit
T _{amb} = 2	5 °C; C _L = 5 pF					
t _{pd}	propagation delay	A, B to Y; see <u>Fig. 4</u> [2]				
		V _{CC} = 0.8 V	-	17.5	-	ns
		V _{CC} = 1.1 V to 1.3 V	2.5	5.3	11.0	ns
		V _{CC} = 1.4 V to 1.6 V	2.0	3.8	6.8	ns
		V _{CC} = 1.65 V to 1.95 V	1.6	3.1	5.3	ns
		V_{CC} = 2.3 V to 2.7 V	1.3	2.5	4.0	ns
		V _{CC} = 3.0 V to 3.6 V	1.0	2.2	3.6	ns

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Low-power 2-input NAND gate

Symbol	Parameter	Conditions	Min	Typ [1]	Max	Unit
T _{amb} = 2	25 °C; C _L = 10 pF					
t _{pd}	propagation delay	A, B to Y; see <u>Fig. 4</u> [2]				
		V _{CC} = 0.8 V	-	21.0	-	ns
		V _{CC} = 1.1 V to 1.3 V	2.4	6.1	13.0	ns
		V _{CC} = 1.4 V to 1.6 V	2.4	4.4	7.9	ns
		V _{CC} = 1.65 V to 1.95 V	2.0	3.7	6.2	ns
		V _{CC} = 2.3 V to 2.7 V	1.4	3.0	4.7	ns
		V _{CC} = 3.0 V to 3.6 V	1.3	2.8	4.3	ns
T _{amb} = 2	25 °C; C _L = 15 pF	· · ·				
t _{pd}	propagation delay	A, B to Y; see <u>Fig. 4</u> [2]				
		V _{CC} = 0.8 V	-	24.5	-	ns
		V _{CC} = 1.1 V to 1.3 V	3.4	6.9	14.8	ns
		V _{CC} = 1.4 V to 1.6 V	2.8	5.0	8.9	ns
		V _{CC} = 1.65 V to 1.95 V	2.0	4.1	7.0	ns
		V _{CC} = 2.3 V to 2.7 V	1.7	3.5	5.3	ns
		V _{CC} = 3.0 V to 3.6 V	1.6	3.2	4.9	ns
T _{amb} = 2	25 °C; C _L = 30 pF					
t _{pd}	propagation delay	A, B to Y; see <u>Fig. 4</u> [2]				
		V _{CC} = 0.8 V	-	34.8	-	ns
		V _{CC} = 1.1 V to 1.3 V	4.6	9.2	20.1	ns
		V _{CC} = 1.4 V to 1.6 V	3.0	6.5	11.8	ns
		V _{CC} = 1.65 V to 1.95 V	2.6	5.4	9.3	ns
		V _{CC} = 2.3 V to 2.7 V	2.4	4.6	7.1	ns
		V _{CC} = 3.0 V to 3.6 V	2.3	4.3	6.5	ns
T _{amb} = 2	25 °C					
C _{PD}	power dissipation	$f = 1 \text{ MHz}; V_I = GND \text{ to } V_{CC}$ [3]				
	capacitance	V _{CC} = 0.8 V	-	2.6	-	pF
		V _{CC} = 1.1 V to 1.3 V	-	2.8	-	pF
		V _{CC} = 1.4 V to 1.6 V	-	2.9	-	pF
		V _{CC} = 1.65 V to 1.95 V	-	3.1	-	pF
		V _{CC} = 2.3 V to 2.7 V	-	3.6	-	pF
		V _{CC} = 3.0 V to 3.6 V	-	4.2	-	pF

[1] All typical values are measured at nominal V_{CC}.

[1] Fin typical values are instantial total to the function of the same as t_{PLH} and t_{PHL} . [2] t_{pd} is the same as t_{PLH} and t_{PHL} . [3] C_{PD} is used to determine the dynamic power dissipation (P_D in μ W). $P_D = C_{PD} \times V_{CC}^2 \times f_i \times N + \Sigma(C_L \times V_{CC}^2 \times f_o)$ where:

f_i = input frequency in MHz;

 f_o = output frequency in MHz;

 C_L = output load capacitance in pF;

 V_{CC} = supply voltage in V;

N = number of inputs switching; $\Sigma(C_L \times V_{CC}^2 \times f_o)$ = sum of the outputs.

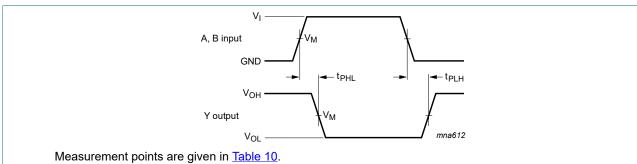
Table 9. Dynamic characteristics

Voltages are referenced to GND (ground = 0 V); for test circuit see Fig. 5

Symbol	Parameter	Conditions	-40 °C to +85 °C		-40 °C to +125 °C		Unit
			Min	Max	Min	Max	
C _L = 5 p	F						
t _{pd}	propagation delay	A, B to Y; see <u>Fig. 4</u> [1]					
		V _{CC} = 1.1 V to 1.3 V	2.1	12.2	2.1	13.5	ns
		V _{CC} = 1.4 V to 1.6 V	1.8	7.8	1.8	8.6	ns
		V _{CC} = 1.65 V to 1.95 V	1.4	6.2	1.4	6.9	ns
		V _{CC} = 2.3 V to 2.7 V	1.1	4.7	1.1	5.2	ns
		V _{CC} = 3.0 V to 3.6 V	1.0	4.2	1.0	4.7	ns
C _L = 10	pF	· · · ·					
t _{pd}	propagation delay	A, B to Y; see <u>Fig. 4</u> [1]					
		V _{CC} = 1.1 V to 1.3 V	2.2	14.4	2.2	15.9	ns
		V _{CC} = 1.4 V to 1.6 V	2.2	9.2	2.2	10.2	ns
		V _{CC} = 1.65 V to 1.95 V	1.9	7.3	1.9	8.1	ns
		V _{CC} = 2.3 V to 2.7 V	1.3	5.6	1.3	6.2	ns
		V _{CC} = 3.0 V to 3.6 V	1.2	4.9	1.2	5.4	ns
C _L = 15	pF						
t _{pd}	propagation delay	A, B to Y; see <u>Fig. 4</u> [1]					
		V _{CC} = 1.1 V to 1.3 V	3.1	16.5	3.1	18.2	ns
		V _{CC} = 1.4 V to 1.6 V	2.5	10.5	2.5	11.6	ns
		V _{CC} = 1.65 V to 1.95 V	2.0	8.3	2.0	9.2	ns
		V_{CC} = 2.3 V to 2.7 V	1.5	6.4	1.5	7.1	ns
		V _{CC} = 3.0 V to 3.6 V	1.4	5.7	1.4	6.3	ns
C _L = 30	pF						
t _{pd}	propagation delay	A, B to Y; see <u>Fig. 4</u> [1]					
		V _{CC} = 1.1 V to 1.3 V	4.1	22.6	4.1	24.9	ns
		V _{CC} = 1.4 V to 1.6 V	2.9	14.0	2.9	15.4	ns
		V _{CC} = 1.65 V to 1.95 V	2.3	11.1	2.3	12.3	ns
		V _{CC} = 2.3 V to 2.7 V	2.1	8.5	2.1	9.4	ns
		V _{CC} = 3.0 V to 3.6 V	2.1	7.6	2.1	8.4	ns

[1] t_{pd} is the same as t_{PLH} and t_{PHL} .

11.1. Waveforms and test circuit



Logic levels: V_{OL} and V_{OH} are typical output voltage drop that occur with the output load.

Fig. 4. The data input (A or B) to output (Y) propagation delays

Table 10. Measurement points

Supply voltage	Input	Output		
V _{cc}	V _M	VI	$t_r = t_f$	V _M
0.8 V to 3.6 V	0.5 × V _{CC}	V _{CC}	≤ 3.0 ns	$0.5 \times V_{CC}$

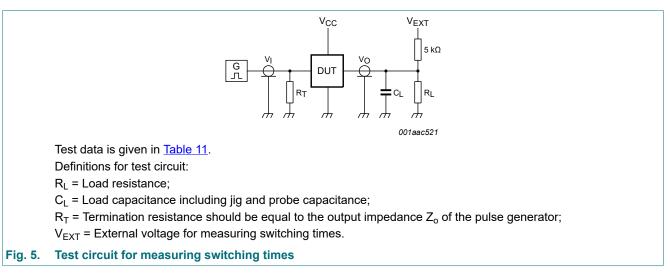


Table 11. Test data

Supply voltage	Load		V _{EXT}		
V _{cc}	CL	R _L [1]	t _{PLH} , t _{PHL}	t _{PZH} , t _{PHZ}	t _{PZL} , t _{PLZ}
0.8 V to 3.6 V	5 pF, 10 pF, 15 pF and 30 pF	5 kΩ or 1 MΩ	open	GND	2 × V _{CC}

[1] For measuring enable and disable times $R_L = 5 k\Omega$.

For measuring propagation delays, setup and hold times and pulse width R_L = 1 M Ω .

12. Package outline

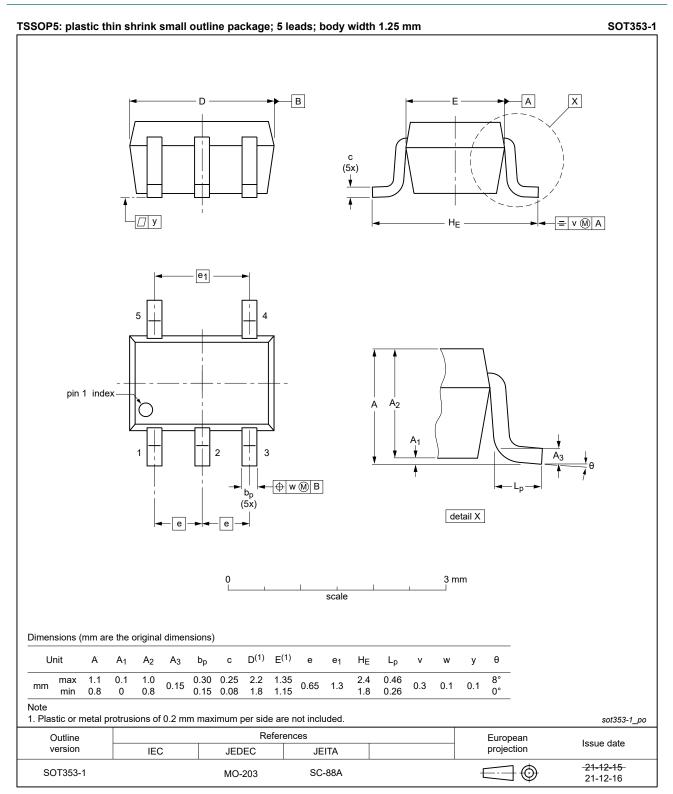


Fig. 6. Package outline SOT353-1 (TSSOP5)

Low-power 2-input NAND gate

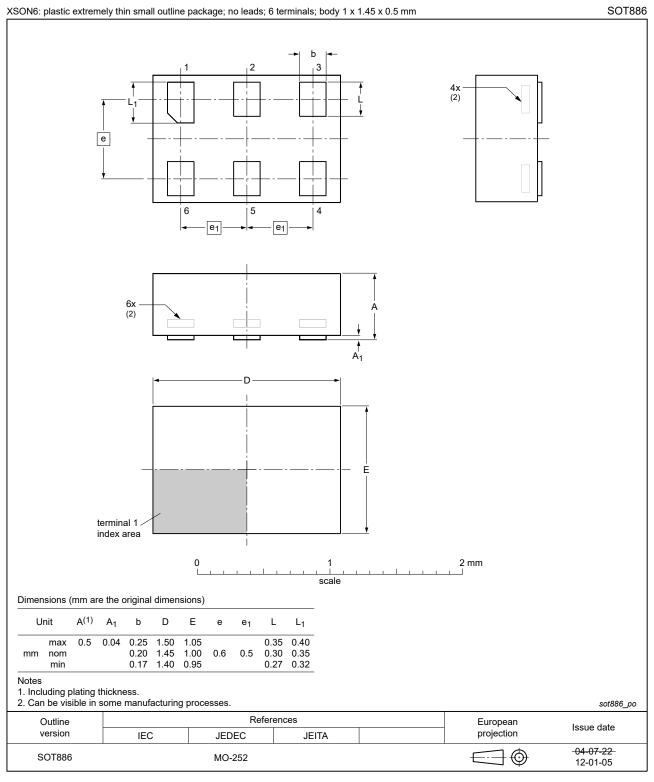
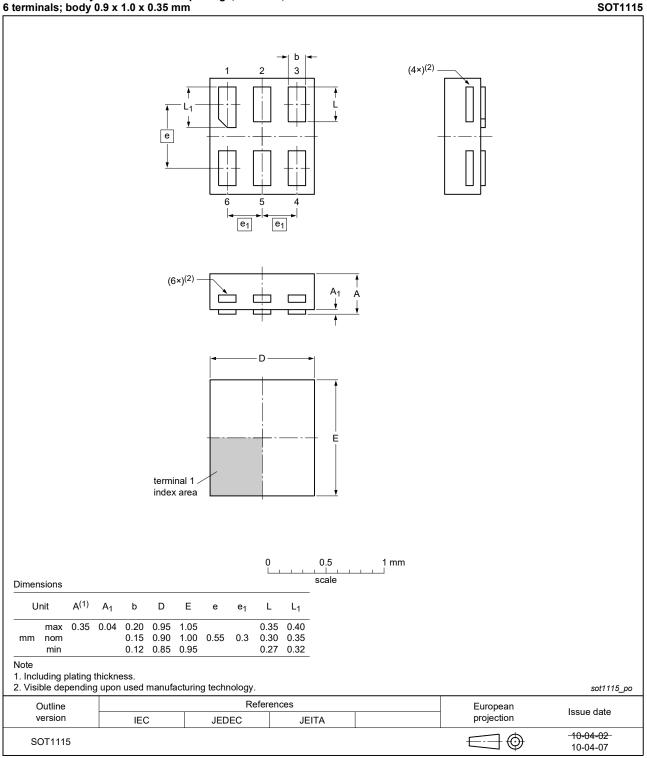


Fig. 7. Package outline SOT886 (XSON6)

Low-power 2-input NAND gate

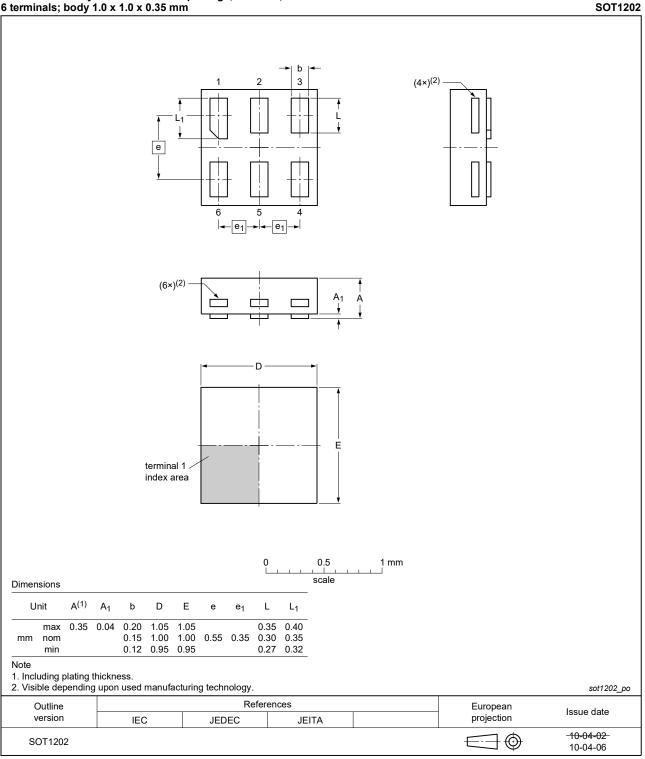
XSON6: extremely thin small outline package; no leads; 6 terminals; body 0.9 x 1.0 x 0.35 mm





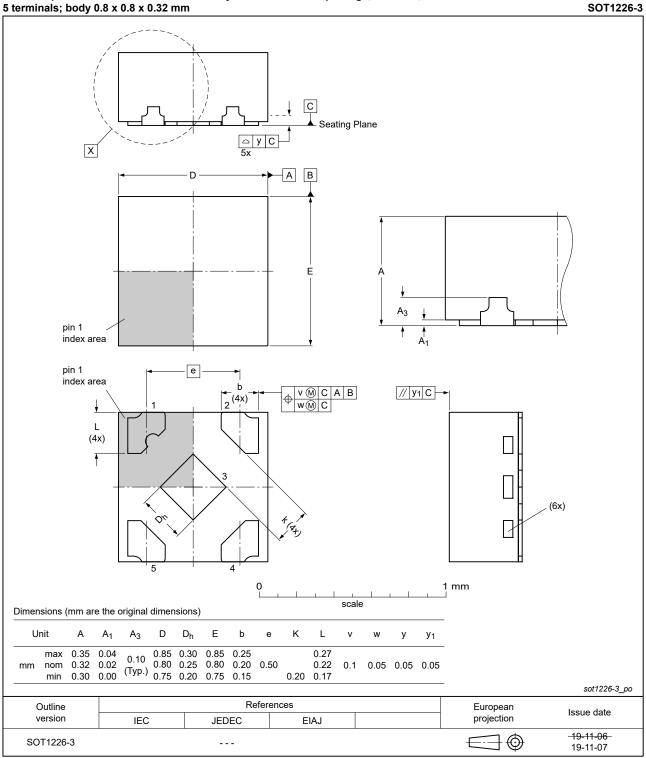
Low-power 2-input NAND gate

XSON6: extremely thin small outline package; no leads; 6 terminals; body 1.0 x 1.0 x 0.35 mm





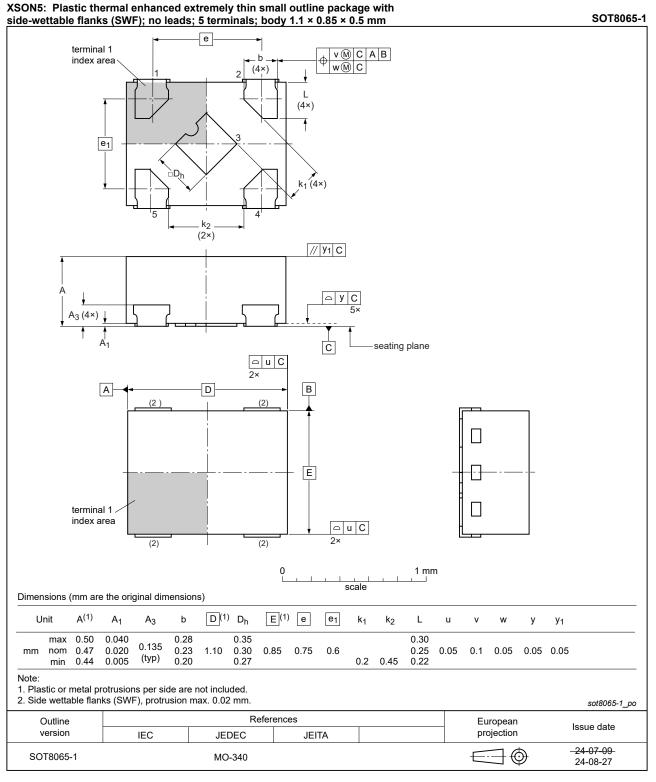
Low-power 2-input NAND gate



X2SON5: plastic thermal enhanced extremely thin small outline package; no leads; 5 terminals; body 0.8 x 0.8 x 0.32 mm

Fig. 10. Package outline SOT1226-3 (X2SON5)

Low-power 2-input NAND gate





13. Abbreviations

Table 12. Abbreviations				
Acronym	Description			
ANSI	American National Standards Institute			
CDM	Charged Device Model			
DUT	Device Under Test			
ESD	ElectroStatic Discharge			
ESDA	ElectroStatic Discharge Association			
HBM	Human Body Model			
JEDEC	Joint Electron Device Engineering Council			

14. Revision history

Table 13. Revision history Release date **Document ID** Data sheet status Change notice Supersedes 74AUP1G00 v.10 20240919 Product data sheet 74AUP1G00 v.9.1 Modifications: Type number 74AUP1G00GZ (SOT8065-1/XSON5) added. 74AUP1G00 v.9.1 Product data sheet 74AUP1G00 v.8 20230711 Modifications: Section 2: ESD specification updated according to the latest JEDEC standard. 74AUP1G00 v.8 20220113 Product data sheet 74AUP1G00 v.7 Modifications: Section 1 and Section 2 updated. Table 5: Derating values for P_{tot} total power dissipation updated. Type number 74AUP1G00GF (SOT891) removed. SOT1226 (X2SON5) package changed to SOT1226-3 (X2SON5) package. Fig. 6: Package outline drawing for SOT353-1 (TSSOP5) has changed. 74AUP1G00 v.7 20190423 Product data sheet 74AUP1G00 v.6 Modifications: The format of this data sheet has been redesigned to comply with the identity guidelines of Nexperia. Legal texts have been adapted to the new company name where appropriate. • Pin configuration drawing SOT1226 (X2SON5) updated. 74AUP1G00 v.6 20120627 Product data sheet 74AUP1G00 v.5 Modifications: Added type number 74AUP1G00GX (SOT1226). • 74AUP1G00 v.5 20120316 Product data sheet 74AUP1G00 v.4 Modifications: Package outline drawing of SOT886 (Fig. 7) modified. 74AUP1G00 v.4 20111115 Product data sheet 74AUP1G00 v.3 Modifications: • Legal pages updated. 74AUP1G00 v.3 20101007 Product data sheet 74AUP1G00 v.2 74AUP1G00 v.2 Product data sheet 74AUP1G00 v.1 20060629 _ 74AUP1G00 v.1 20050711 Product data sheet

15. Legal information

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Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

 Please consult the most recently issued document before initiating or completing a design.

- [2] The term 'short data sheet' is explained in section "Definitions".
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